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(71) Applicant: **IBIDEN CO., LTD.**
Ogaki-shi Gifu-ken 503-0917 (JP)

(72) Inventors:
• **EN, Honchin**
Ibi-gun, Gifu 501-0695 (JP)

- **NAKAI, Tohru**
Ibi-gun, Gifu 501-0695 (JP)
- **OKI, Takeo**
Tsushima-shi, Aichi 496-0807 (JP)
- **HIROSE, Naohiro**
Ibi-gun, Gifu 501-0695 (JP)
- **NODA, Kouta**
Ibi-gun, Gifu 501-0695 (JP)

(74) Representative:
Leson, Thomas Johannes Alois, Dipl.-Ing.
Tiedtke-Bühling-Kinne & Partner GbR,
TBK-Patent,
Bavarlaring 4
80336 München (DE)

(54) **PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD**

(57) A method for manufacturing a printed wiring board having a high-density wiring and a highly-reliable connection between conductor layers even if the annealing process is omitted because a conductor circuit made of an electroplating layer excellent in crystallinity and uniform electrodepositability and formed on a base sheet and a via hole are provided. The method comprising forming an interlayer resin insulating layer on a conductor wiring forming board, making an opening for making a via hole in the interlayer resin insulating layer, forming an electroless plating layer (1008) on the inter-

layer resin insulating layer, applying a resist film (1003) to the layer (1008), forming an electroplating film thereon, removing the resist film, and removing the electroless plating layer by etching so as to form a conductor wiring and a via hole characterized in that the electroless plating layer (1008) serves as a cathode, the plating metal serves as an anode, and electroplating is performed intermittently while maintaining the voltage between the anode and cathode at a constant value.

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